



Material Content Data Sheet



Sales Product Name	TLE6208-3G			Issued	28. August 2013			
MA#	MA000982028							
Package	PG-DSO-14-35			Weight*	144.83 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	8.287	5.72	5.72	57219	57219
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		104	
	non noble metal	zinc	7440-66-6	0.060	0.04		417	
	non noble metal	iron	7439-89-6	1.207	0.83		8333	
wire	non noble metal	copper	7440-50-8	49.007	33.84	34.72	338365	347219
	noble metal	gold	7440-57-5	0.814	0.56	0.56	5618	5618
	encapsulation	organic material	carbon black	1333-86-4	0.161	0.11		1112
plastics		epoxy resin	-	7.411	5.12		51169	
	inorganic material	silicondioxide	60676-86-0	72.982	50.39	55.62	503900	556181
leadfinish	non noble metal	tin	7440-31-5	1.226	0.85	0.85	8466	8466
plating	noble metal	silver	7440-22-4	1.030	0.71	0.71	7110	7110
glue	plastics	acrylic resin	-	0.580	0.40		4001	
	noble metal	silver	7440-22-4	2.055	1.42	1.82	14186	18187
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

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